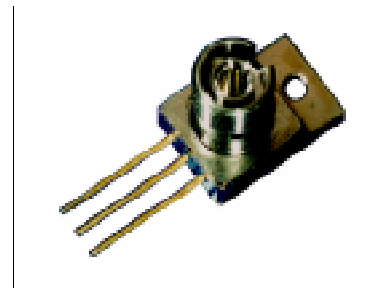


Laser Diode in TO-220 Package with FC-connector 0.75 W cw (Class 4 Laser Product)

SPL 2Fxx
(SFH 4874x6)

Features

- Efficient radiation source for pulsed and cw-operation
- Reliable InGa(Al)As strained quantum-well material
- Small TO-220 package with efficient thermal coupling
- Includes thermistor to control temperature/wavelength
- Single emitting area $200 \mu\text{m} \times 1 \mu\text{m}$
- FC-type connector for efficient fiber coupling



Applications

- Pumping solid state lasers (Nd: YAG, Yb: YAG, ...)
- Medical applications
- Laser soldering
- Energy transmission
- Testing and measuring applications

Type	Old Type (as of Oct. 1996)	Wavelength ^{*)}	Ordering Code
SPL 2F81	SFH 487406	808 nm	Q62702-P368
SPL 2F85	SFH 487426	850 nm	Q62702-P1678
SPL 2F94	SFH 487446	940 nm	Q62702-P1631

^{*)} Other wavelengths in the range of 780 nm ... 980 nm are available on request.

Maximum Ratings

($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Output power (continuous wave) ¹⁾	P_{opt}	—	—	0.8	W
Output power (quasi-continuous wave) ¹⁾ ($t_p \leq 150 \mu\text{s}$, duty cycle $\leq 1\%$)	P_{qcw}	—	—	1.1	W
Reverse voltage	V_R	—	—	3	V
Operating temperature	T_{op}	— 10	...	+ 60	$^\circ\text{C}$
Storage temperature	T_{stg}	— 40	...	+ 70	$^\circ\text{C}$
Maximum soldering temperature, max. 5 s	T_s	—	—	250	$^\circ\text{C}$

1) Optical data refer to output after a fiber of 5 m length (core $\varnothing 125 \mu\text{m}$, 0.35 NA, attn. 8 db/km)

Diode Characteristics

($T_A = 25\text{ °C}$)

Parameter	Symbol	Values			Unit	
		min.	typ.	max.		
Emission wavelength ¹⁾	λ_{peak}	803 840 935	808 850 940	813 860 945	nm	
Spectral width (FWHM) ¹⁾	$\Delta\lambda$	2			nm	
Output power ²⁾	P_{opt}	0.75			W	
Differential efficiency ²⁾	η	808 nm 850 nm 940 nm	0.60 0.60 0.55	0.70 0.70 0.60	0.85 0.80 0.70	W/A
Threshold current	I_{th}	808 nm 850 nm 940 nm	0.40 0.30 0.30	0.45 0.40 0.35	0.55 0.50 0.40	A
Operating current ¹⁾	I_{op}	808 nm 850 nm 940 nm	1.3 1.3 1.4	1.5 1.5 1.6	1.8 1.8 1.8	A
Operating voltage ¹⁾	V_{op}	2.0			V	
Differential series resistance	r_{s}	0.2		0.4	Ω	
Characteristic temperature (threshold) ³⁾	T_0	150			K	
Temperature coefficient of current	$\partial I_{\text{op}} / \partial T$	0.5			%/K	
Temperature coefficient of wavelength ⁴⁾	$\partial \lambda / \partial T$	0.25	0.27	0.30	nm/K	
Thermal resistance (junction → heat sink)	$R_{\text{th JA}}$	10			K/W	

1) Standard operating conditions refer to 0.75 W after 5 m of fiber (core \varnothing 125 μm , 0.35 NA, attn. 8 db/km)

2) Optical power measurements refer to output from fiber

3) Model for the thermal behavior of threshold current: $I_{\text{th}}(T_2) = I_{\text{th}}(T_1) \times \exp(T_2 - T_1)/T_0$

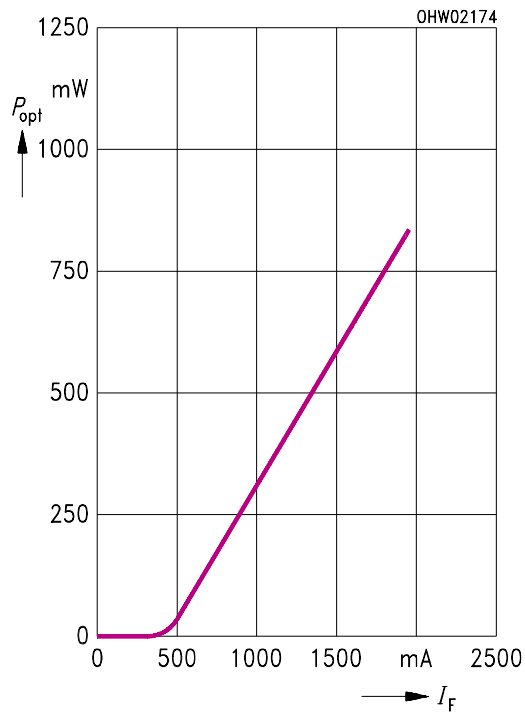
4) Depending on emission wavelength

NTC Thermistor

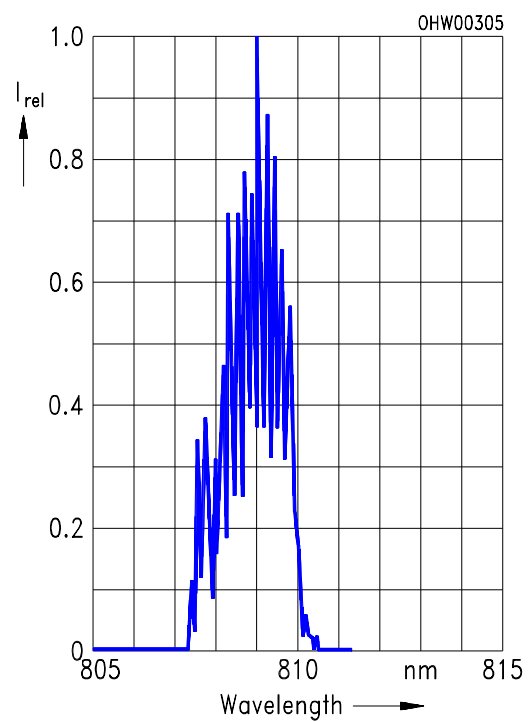
Parameter	Symbol	Typ. Values	Unit
Resistance at room temperature (25 °C)	R_{NTC}	10	k Ω

Optical Characteristics ($T_A = 25\text{ °C}$)

Radiant Power P_{opt} vs I_F

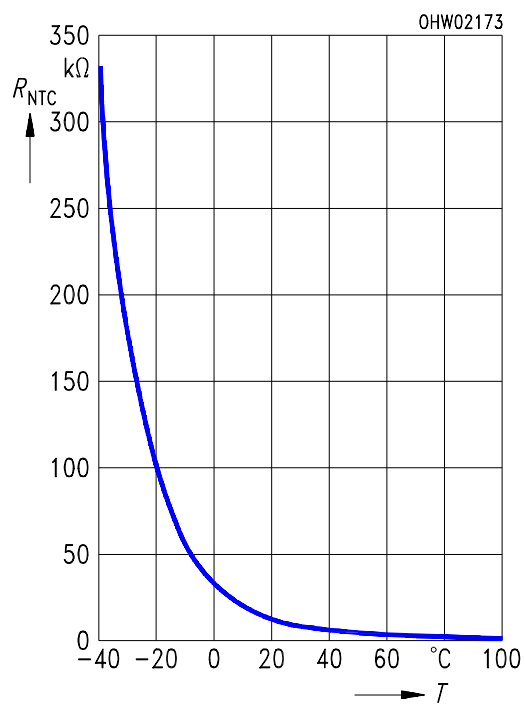


Mode Spectrum I_{rel} vs λ ($P_{\text{opt}} = 1.0\text{ W}$)



NTC Thermistor $R_T = f(T_A)$

$R_{T\ 25\text{ °C}} = 10\text{ k}\Omega \pm 1\%$



Notes for Operation

1. Eye Protection

This laser is a **Class 4 Laser** product.

Refer to the relevant safety regulations for protection during handling and operation.

2. Overload Protection

The specified values are valid as long as the diode has not been not overloaded. Voltage spikes from the power supply unit, even when applied for nanoseconds only, may cause irreversible damage to the laser diode. Such spikes may occur when the power supply is turned on or off, or they may reach the laser diode from the line via the coupling capacitance of electronically controlled devices.

The power supply should therefore be provided with appropriate protection circuits.

Handling Notes

1. Package

To avoid electrostatic damage it is recommended to observe the same rules as for handling MOS-devices.

2. Mechanical Attachment

2.1 Mounting hole (suitable for M 2.5)

Because of the good thermal conductivity of the TO 220 base plate (copper) the heat loss is properly dissipated even if the component is attached on one side only. Some mounting techniques are shown below (**Fig. 1 – 3**).

2.2 For exact positioning of the TO component and other parts, e.g. lenses, the TO 220 package can be attached with appropriate clamping devices or screws (max. M 2.5).

3. Soldering

When soldering the TO base to a heat sink, do not exceed the following limits:

- max. soldering temperature: 125 °C
- max. soldering time: 1 min.

Mounting Techniques

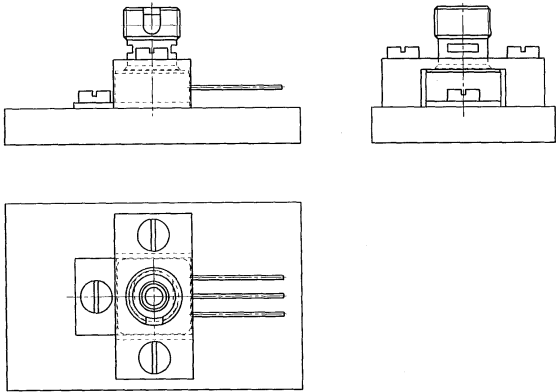


Figure 1

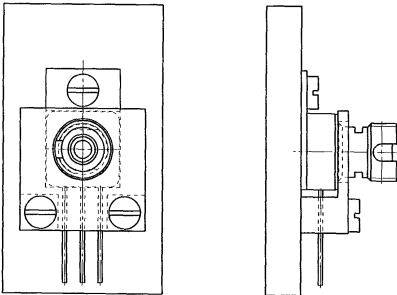


Figure 2

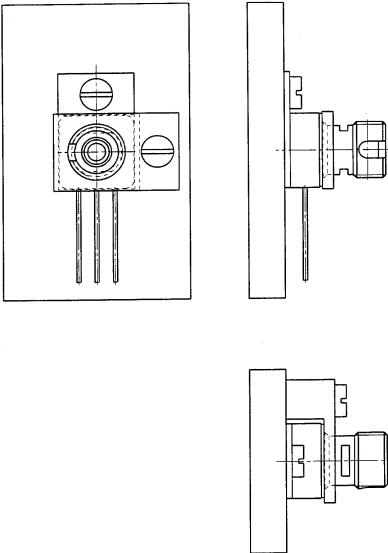


Figure 3

(Dimensions in mm, unless specified).

